

Amendments to the Claims

Listing of Claims:

Claims 1 - 9 (canceled).

Claim 10 (currently amended). An optical module, comprising:

a circuit carrier;

a semiconductor element disposed in a housing disposed on said circuit carrier, said housing of said semiconductor element, at least in sections thereof, having a support formed thereon; and

a lens unit configured for projecting electromagnetic radiation onto said semiconductor element, said lens unit including a base lens;

wherein said semiconductor element and said lens unit are formed in two parts, ~~said lens unit is supported on said base lens, and~~ and said base lens is supported on and in direct contact with said support formed on said housing of said semiconductor element.

Claim 11 (previously presented). The optical module according to claim 10, wherein said support is formed to be substantially tilt-free.

Claim 12 (previously presented). The optical module according to claim 10, wherein said support is a ring collar.

Claim 13 (canceled).

Claim 14 (previously presented). The optical module according to claim 10, wherein said base lens includes a surface section formed to correspond to said support, at least in sections thereof, and wherein said surface section is positioned on said support formed on said housing of said semiconductor element.

Claim 15 (previously presented). The optical module according to claim 10, wherein said base lens has a collar, at least in sections thereof, formed to correspond substantially to a locating face formed on said support.

Claim 16 (currently amended). ~~The optical module according to claim 10, wherein~~
An optical module, comprising:

a circuit carrier;

a semiconductor element disposed in a housing disposed on said circuit carrier, said housing of said semiconductor element, at least in sections thereof, having a support formed thereon; and

a lens unit configured for projecting electromagnetic radiation onto said semiconductor element, said lens unit including a base lens;

wherein said semiconductor element and said lens unit are formed in two parts and said base lens is supported on and in direct contact with said support formed on said housing of said semiconductor element; and

wherein said lens unit includes a lens holder and said lens holder is supported by said circuit carrier substantially without being supported by said housing.

Claim 17 (previously presented). The optical module according to claim 16, wherein said lens holder includes a surface section formed to correspond to said support, at least in sections thereof, and wherein said surface section is positioned on said support formed on said housing of said semiconductor element.

Claim 18 (previously presented). The optical module according to claim 16, wherein said lens holder has a collar, at least in sections thereof, formed to correspond substantially to a locating face formed on said support.

Claim 19 (previously presented). The optical module according to claim 10, wherein said support is formed with a locating face, at least in sections thereof.

Claim 20 (previously presented). The optical module according to claim 19, wherein said locating face of said support is formed with a taper from said semiconductor element in a direction of an optical axis of the optical module.

Claim 21 (previously presented). The optical module according to claim 20, wherein said taper is conical.

Claim 22 (previously presented). An optical system, comprising an optical module according to claim 10.